



## Final Product Change Notification

201412008F01

**Issue Date:** 01-Apr-2015

**Effective Date:** 15-Jul-2015

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# QUALITY

### Change Category

- |  |  |   |  |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking                | <input type="checkbox"/> Design                    |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification  |
| <input type="checkbox"/> Wafer Fab location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Test Location                  | <input type="checkbox"/> Packing/Shipping/Labeling |

**Change of bond wire and release of 2nd source mold compound in DFN2020-3 (SOT1061)**

### Details of this Change

Scheduled changes affect Schottky barrier rectifiers in DFN2020-3 (SOT1061) package only.

- (1) The bond wire material will be changed from gold to copper. Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound supplier will be introduced.

Old product: Wire material is gold (Au) (with currently used mold compound suppliers)

Changed product: Wire material is copper (Cu) or gold (Au) (with currently used first and new second source mold compound supplier)

The design and materials of all other components will remain unchanged: die, die attach, and lead frame.

Reliability qualification and full electrical characterization over temperature have been performed. For details please see the Self Qualification Report.

No change on thermal behavior or mechanical dimensions. Electrical parameters will remain unchanged (in specification and with the same distribution).

### Why do we Implement this Change

(1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.

(2) Following NXP company policy of second source material availability, a second source mold compound will be added to the BOM for associated types in DFN2020-3 (SOT1061) package. The second source supplier is already well established for NXP semiconductor products.

### Identification of Affected Products

Changed products can be identified by date code after implementation.

## Product Availability

### Sample Information

Samples are available upon request

Latest sample request date for PCN samples is 30-Apr-2015.

### Production

Planned first shipment 15-Jul-2015

### Impact

No impact to the products' functionality anticipated.

### Disposition of Old Products

Existing inventory will be shipped until depleted

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 01-May-2015.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** GA Customer Support

**e-mail address** DiscrQA.Helpdesk.GA-Products@nxp.com

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NXP Quality Management Team.

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Customer Part#	Changed Part 12NC
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PMEG6020EPA,115	934063487115
PMEG2020EPA,115	934064295115
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